## BCX17LT1G, PNP BCX18LT1G, PNP BCX19LT1G, NPN SBCX19LT1G, NPN

# **General Purpose Transistors**

# Voltage and Current are Negative for PNP Transistors

## Features

- S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant\*

## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage BCX17, BCX19 BCX18	V <sub>CEO</sub>	45 25	Vdc
Collector – Base Voltage BCX17, BCX19 BCX18	V <sub>CBO</sub>	50 30	Vdc
Emitter – Base Voltage	V <sub>EBO</sub>	5.0	Vdc
Collector Current – Continuous	۱ <sub>C</sub>	500	mAdc

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1), $T_A = 25^{\circ}C$ Derate above 25°C	P <sub>D</sub>	225	mW mW/°C
		1.8	mw/ C
Thermal Resistance, Junction-to-Ambient	$R_{\thetaJA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction–to–Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-5 = 1.0  $\times$  0.75  $\times$  0.062 in.

2. Alumina = 0.4  $\times$  0.3  $\times$  0.024 in 99.5% alumina.

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

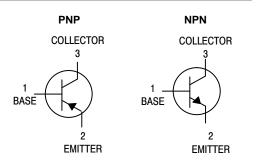


## **ON Semiconductor®**

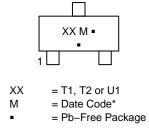
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(TO-236) CASE 318-08 STYLE 6



## MARKING DIAGRAM



(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

## **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

## BCX17LT1G, PNP BCX18LT1G, PNP BCX19LT1G, NPN SBCX19LT1G, NPN

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector–Emitter Breakdown Voltage $(I_C = 10 \text{ mAdc}, I_B = 0)$ BCX17, BCX19, SBCX19	V <sub>(BR)CEO</sub>	45	_	_	Vdc
BCX18		25	-	-	
Collector–Emitter Breakdown Voltage $(I_{C} = 10 \ \mu Adc, I_{C} = 0)$	V <sub>(BR)CES</sub>				Vdc
BCX17, BCX19, SBCX19 BCX18		50 30			
Collector Cutoff Current $(V_{CB} = 20 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 20 \text{ Vdc}, I_E = 0, T_A = 150^{\circ}\text{C})$	І <sub>СВО</sub>	-		100 5.0	nAdc μAdc
Emitter Cutoff Current ( $V_{EB} = 5.0 \text{ Vdc}, I_C = 0$ )	I <sub>EBO</sub>	_	_	10	μAdc
ON CHARACTERISTICS				1	
DC Current Gain ( $I_C = 100 \text{ mAdc}$ , $V_{CE} = 1.0 \text{ Vdc}$ ) ( $I_C = 300 \text{ mAdc}$ , $V_{CE} = 1.0 \text{ Vdc}$ ) ( $I_C = 500 \text{ mAdc}$ , $V_{CE} = 1.0 \text{ Vdc}$ )	h <sub>FE</sub>	100 70 40		600 _ _	_
Collector–Emitter Saturation Voltage $(I_C = 500 \text{ mAdc}, I_B = 50 \text{ mAdc})$	V <sub>CE(sat)</sub>	-	-	0.62	Vdc
Base–Emitter On Voltage (I <sub>C</sub> = 500 mAdc, V <sub>CE</sub> = 1.0 Vdc)	V <sub>BE(on)</sub>	_	_	1.2	Vdc

#### **ORDERING INFORMATION**

Device	Specific Marking	Package	Shipping <sup>†</sup>
BCX17LT1G	T1	SOT-23 (Pb-Free)	3,000 / Tape & Reel
NSVBCX17LT1G*	T1	SOT-23 (Pb-Free)	3,000 / Tape & Reel
BCX18LT1G	T2	SOT-23 (Pb-Free)	3,000 / Tape & Reel
BCX19LT1G	U1	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SBCX19LT1G*	U1	SOT-23 (Pb-Free)	3,000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. \*S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and

PPAP Capable.

## BCX17LT1G, PNP BCX18LT1G, PNP BCX19LT1G, NPN SBCX19LT1G, NPN

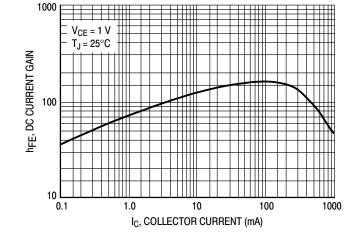
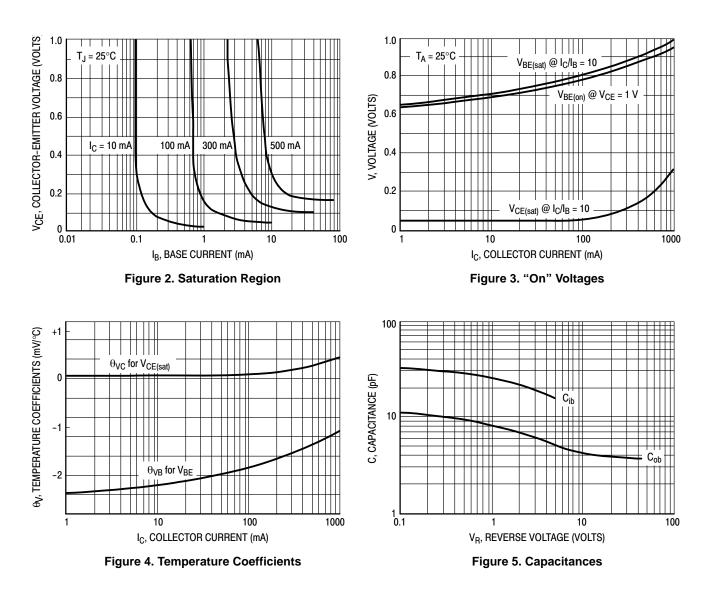


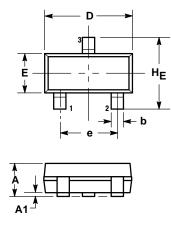
Figure 1. DC Current Gain

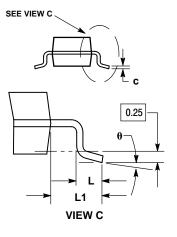


## BCX17LT1G, PNP BCX18LT1G, PNP BCX19LT1G, NPN SBCX19LT1G, NPN

### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AP





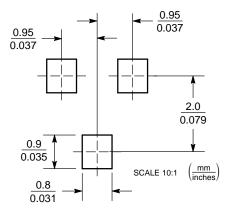
NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
  - MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- THICKNESS OF BASE MATERIAL. 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°		10°	0°		10°

STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR

#### SOLDERING FOOTPRINT



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BCX17LT1/D